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Hobart, K.D.; Kub, F.J.; Jernigan, G.G.; Twigg, M.E.; Thompson, P.E.;

Electronics Letters, Volume: 34, Issue: 12, 11 June 1998

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2 Ultra-cut: a simple technique for the fabrication of SOI substrates with ultra-thin (<5 nm) silicon films

Hobart, K.D.; Kub, F.J.; Twigg, M.E.; Jernigan, G.G.; Thompson, P.E.;

SOI Conference, 1998. Proceedings., 1998 IEEE International, 5-8 Oct. 1998

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3 SOI on buried cavity patterns using ion-cut layer transfer

Yun, C.H.; Cheung, N.W.;

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4 CMOS on bonded wafers fabricated using a novel Si-Ge etch stop

King, E.E.; Huang, D.H.; Leonov, P.; Palkuti, L.J.; Campisi, G.J.; Hughes, H.L.; Godbey, D.J.;

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5 A new method of forming a thin single-crystal silicon diaphragm using merged epitaxial lateral overgrowth for sensor applications

Pak, J.J.; Neudeck, G.W.; Kabir, A.E.; DeRoo, D.W.; Staller, S.E.;

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6 Highly uniform SOI fabrication by applying voltage during KOH etching of bonded wafers

Ogura, A.;

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7 Silicon-on-quartz for low power electronic applications

Sarma, K.R.; Liu, S.T.;

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8 Novel high-performance pressure sensors using double SOI structures

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Solid-State Sensors and Actuators, 1991. Digest of Technical Papers,

TRANSDUCERS '91., 1991 International Conference on , 24-27 June 1991

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9 A trench isolated SOI bipolar process

Shain, D.; Badilo, R.;

SOS/SOI Technology Conference, 1990., 1990 IEEE , 2-4 Oct. 1990

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